

LINEAR TECHNOLOGY MATERIALS DECLARATION

1tc3890mpgn-1#pbf

(Engineering Calculation)

SSOP

(printed on: 2020-07-11 22:29:28)

TOTAL MASS (g) : 0.169127

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002090 | 1000000 | 12357.5820312 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.064009 | 975000 | 378467.1875 | | |
| | | Iron (Fe) | 7439-89-6 | 0.001576 | 24000 | 9318.44433594 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000020 | 300 | 118.254364014 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000046 | 700 | 271.985046387 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.065651 | 1000000 | 388175.875 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.003749 | 1000000 | 22166.3769531 | | |
| | | External Plating Total: | | | | 0.003749 | 1000000 | 22166.3769531 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000525 | 1000000 | 3104.17700195 | | |
| Internal Plating Total: | | | | 0.000525 | 1000000 | 3104.17700195 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000709 | 750000 | 4192.1171875 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000236 | 250000 | 1395.40161133 | | |
| Die Attach Total: | | | | 0.000945 | 1000000 | 5587.51855469 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.009848 | 103000 | 58228.4492188 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.085571 | 895000 | 505957.25 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000191 | 2000 | 1129.32922363 | | |
| | | Encapsulation Total: | | | | 0.095610 | 1000000 | 565315 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000557 | 1000000 | 3293.3840332 | | |
| | | | | | TOTAL MASS (g) : | 0.169127 | | |